Product Change Notification

106112 - 01

Information in this document is provided in connection with Intel products. No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Intel's Terms and Conditions of Sale for such products, Intel assumes no liability whatsoever, and Intel disclaims any express or implied warranty, relating to sale and/or use of Intel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright or other intellectual property right. Intel products are not intended for use in medical, life saving, or life sustaining applications. Intel may make changes to specifications and product descriptions at any time, without notice.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2006. Other names and brands may be claimed as the property of others.

Celeron, Centrino, Intel, the Intel logo, Intel Core, Intel NetBurst, Intel NetMerge, Intel NetStructure, Intel SingleDriver, Intel SpeedStep, Intel StrataFlash, Intel Viiv, Intel XScale, Itanium, MMX, Paragon, PDCharm, Pentium, and Xeon are trademarks or registered trademarks of Intel Corporation or its subsidiaries in the United States and other countries.

Learn how to use Intel Trade Marks and Brands correctly at http://www.intel.com/intel/legal/tmusage2.htm.

Product Change Notification

Change Notification #: **106112 - 01**

Change Title: **Intel StrataFlash® Cellular Memory Stacked 512M/128P Solder Ball Alloy Change and RAM Manufacturing Site Proliferation, PCN 106112-01, Product Material, Reason for Revision: Change to Sample Availability and Product Availability**

Date of Publication: **May 22, 2006**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date of Samples Availability:	Jun 30, 2006
Date Customer Must be Ready to Receive Post-Conversion Material:	Aug 25, 2006

Description of Change to the Customer:

Reason for Revision: Change to sample availability & product availability

Intel is changing to solder ball composition on the Intel StrataFlash® Cellular Memory 512M/128P product. In addition, Intel's PSRAM supplier has notified us of a manufacturing site proliferation. This notification encompasses both changes for our customers.

The solder balls will change from a SAC405 alloy to a SAC105 alloy. Intel is also using this opportunity to change the solder resist opening (SRO) on the 512M/128P product from SRO300 to SRO350.

The PSRAM is a Mfg site proliferation only. The material from the new site has the same functional specifications as the existing source. There is no change to the datasheet of the 512M/128P stacked device as a result of this proliferation.

No new ordering codes will be established, current order codes will remain valid (reference Products Affected listing below). There will be a period of time where customers may receive both types of solder alloy material. This period of possible mixed shipments may begin as early as October 13, 2006, and is anticipated to end approximately December 16, 2006 based on current supply line TPT and inventory levels.

Likewise, the PSRAM material from the new Mfg site will ship interchangeably with the current PSRAM source after the "Customer Must be Ready to Receive." milestone shown above.

Customer Impact of Change and Recommended Action:

Intel does not anticipate any change to the SMT (Surface Mount Technology) process, but customers may want to re-characterize their process as they would normally do for new products & packages.

Samples will be available per the milestones above. Customers are encouraged to place orders for samples immediately if there is a need.

Products Affected / Intel Ordering Codes:

Component Product Table

Sample Product Description	Sample Product Code	Sample Production MM#	Package Media
512M/128P	PF38F5060M0Y0C0Q HE6	883743	Tray
512M/128P	PF38F5060M0Y0C0Q HE7	883744	Tape & Reel
512M/128P	PF38F5060M0Y0C0Q HA7	883297	Tube

Component Product Table

Product Description	Product Code	MM#	Package Media
512M/128P	PF38F5060M0Y0C0874324	874324	Tray
512M/128P	PF38F5060M0Y0C0S B48	874319	Tape & Reel
512M/128P	PF38F5060M0Y0C0S B93	874287	Tube

Reference Documents / Attachments:

Document: **Location #:**

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
April 13, 2006	00	Originally Published PCN
May 22, 2006	01	Change to sample availability & product availability